

Technical Data Sheet

MODEL NO: S3014ANWW4-H

3.0 x 1.4 x 0.8mm Warm White SMD

Features

●Package: 4000pcs per reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Dice material	Emitted color	Lens Color	
InGaN	Warm White	Yellow diffused	

Electrical/Optical Characteristics(Ta= 25° C)

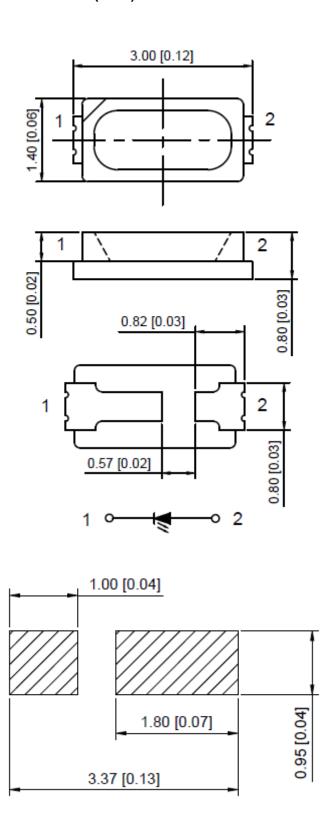
Parameter	Test	Symbol	Value			l lmit
	Condition		Min	Тур	Max	Unit
Luminous Flux	IF=40mA	φ (lm)	13		17	lm
Chromaticity Coordinates	IF=40mA	X	0.409		0.463	-
		Υ	0.394		0.420	-
	IF=40mA		2600		2800	
Color Temperature		CCT	2800		3100	K
			3200		3600	
Color Rendering Index	IF=40mA	Ra	80			-
Forward voltage	IF=40mA	VF	2.7		3.3	V
Viewing angle	IF=40mA	2 0 1/2		120		Deg
Reverse current	V _R =5V	lr			10	μА

Absolute Maximum Ratings(Ta=25°C)

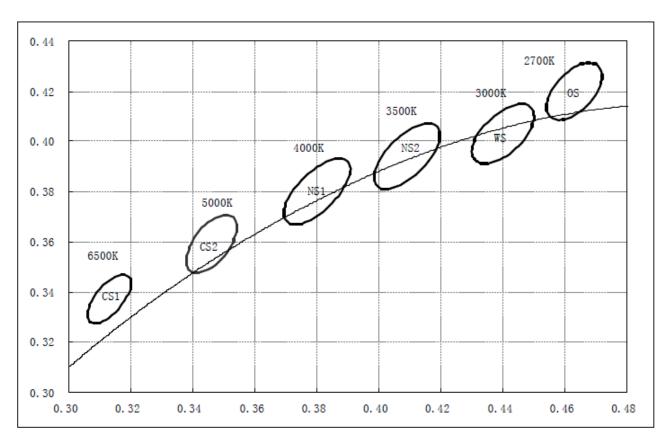
Parameter	Symbol	Value	Unit
Power dissipation	Pd	120	mW
Forward current	lf	40	mA
Reverse voltage	Vr	5	V
Operating temperature range	Тор	-40 ~+85	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+100	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 duty f=1kHz)	IFP	100	mA



PACKAGING DIMENSIONS (mm):



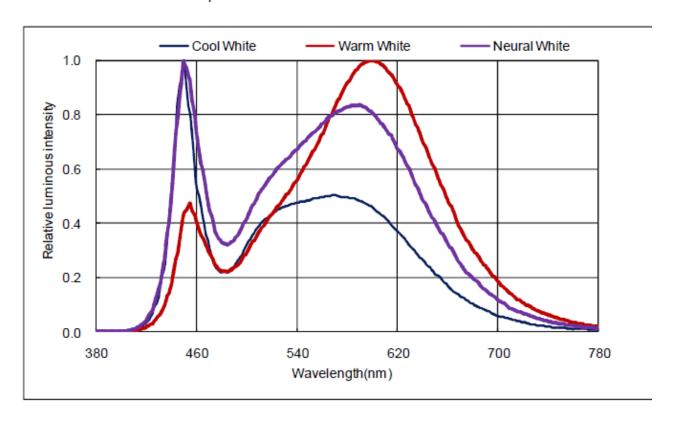




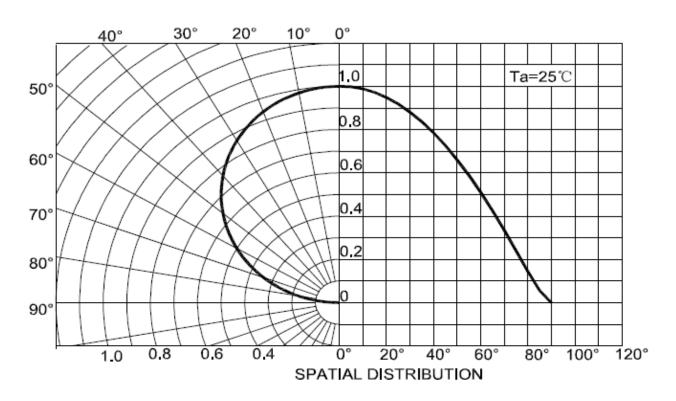
Bin Range of Chromaticity

CCT 色温	Bin Code Bin代码	CIE_x	CIE_y
6500K	CS1 6000-7000K	0.313	0.337
5000K	CS2 4750-5300K	0.346	0.359
4000K	NS1 3800-4250K	0.380	0.380
3400K	NS2 3200-3600K	0.409	0.394
3000K	WS 2800-3100K	0.440	0.403
2700K	OS 2600-2800K	0.463	0.420

Relative spectral emission



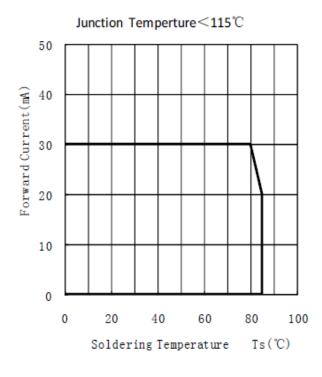
Radiation diagram

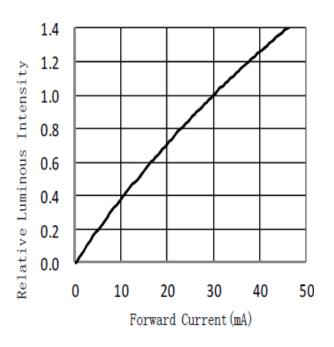




Soldering Temperature vs. Forward Current 焊盘温度与正向电流特性曲线

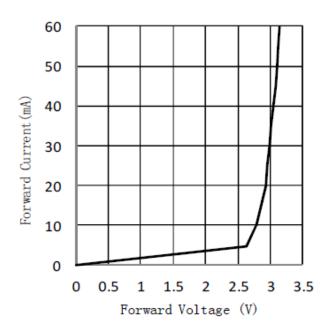
Forward Current VS. Relative Intensity 正向电流与相对光强特性曲线

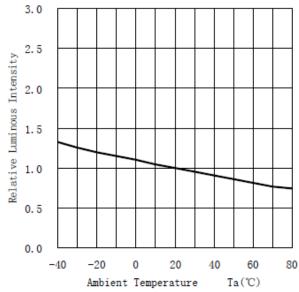




Forward Voltage VS. Forward Current 正向电压与正向电流特性曲线







Precautions For Use:

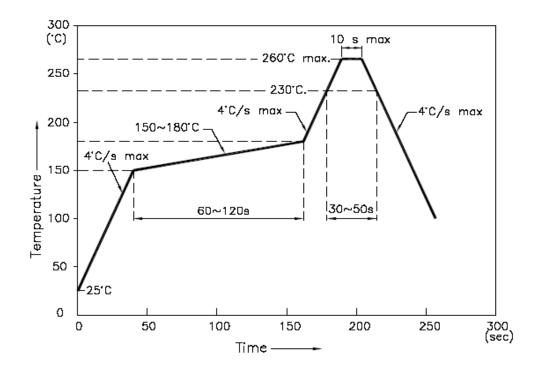
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C \sim 30 $^{\circ}$ C, 60 $^{\circ}$ R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}\mathbb{C}(\pm 5^{\circ}\mathbb{C})$.the maximum soldering temperature should be limited to $260^{\circ}\mathbb{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

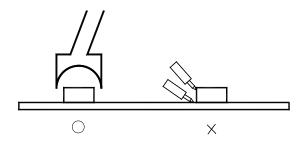


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.